EB3250 Series



REGULATORY COMPLIANCE

Lead Free	EU RoHS	China RoHS	REACH
\bigotimes	2011/65 + 2015/863	e	SVHC
COMPLIANT	COMPLIANT	COMPLIANT	COMPLIANT



ITEM DESCRIPTION

Automotive Grade Quartz Crystal Resonator 3.2mm x 5.0mm x 0.85mm 4 Pad Ceramic Surface Mount (SMD)

ELECTRICAL SPECIFICATIONS		
Nominal Frequency	7.6MHz to 54MHz	
Frequency Tolerance/Stability	\pm 50ppm at 25°C, \pm 100ppm over -40°C to +85°C \pm 30ppm at 25°C, \pm 50ppm over -40°C to +85°C \pm 15ppm at 25°C, \pm 30ppm over -40°C to +85°C \pm 15ppm at 25°C, \pm 20ppm over -40°C to +85°C \pm 10ppm at 25°C, \pm 20ppm over -40°C to +85°C \pm 50ppm at 25°C, \pm 100ppm over -40°C to +105°C \pm 30ppm at 25°C, \pm 50ppm over -40°C to +105°C \pm 50ppm at 25°C, \pm 100ppm over -40°C to +125°C \pm 30ppm at 25°C, \pm 100ppm over -40°C to +125°C	
Aging at 25°C	±3ppm/year Maximum	
Load Capacitance	Series Resonant, 8pF Parallel Resonant to 32pF Parallel Resonant	
Shunt Capacitance	5pF Maximum	
Equivalent Series Resistance	100 Ohms Maximum over Nominal Frequency of 7.6MHz to 11.999999MHz 60 Ohms Maximum over Nominal Frequency of 12MHz to 13.999999MHz 50 Ohms Maximum over Nominal Frequency of 14MHz to 19.999999MHz 40 Ohms Maximum over Nominal Frequency of 20MHz to 54MHz	
Mode of Operation	AT-Cut Fundamental	
Drive Level	300µWatts Maximum	
Crystal Cut	AT-Cut	
Spurious Response	Measured from Fo to Fo +5000ppm -3dB Minimum	
Storage Temperature Range	-50°C to +150°C	
Insulation Resistance	Measured at 100Vdc 500 Megaohms Minimum	

EB3250 Series



PART NUMBERING GUIDE

EB3250 X A 20 -27.000M TR

Series Automotive Quartz Crystal Resonator 3.2mm x 5.0mm

x 0.85mm 4 Pad Ceramic Surface Mount (SMD)

Frequency Tolerance/Stability -C = ±50ppm at 25°C, ±100ppm over -40°C to +85°C F = ±30ppm at 25°C, ±50ppm over -40°C to +85°C J = ±15ppm at 25°C, ±30ppm over -40°C to +85°C $\begin{array}{l} J = \pm 15 ppm \mbox{ at } 25\ C, \ \pm 30 ppm \ over \ -40\ C \ to \ \pm 85\ C \\ M = \pm 15 ppm \mbox{ at } 25\ C, \ \pm 20 ppm \ over \ -40\ C \ to \ \pm 85\ C \\ U = \pm 10 ppm \mbox{ at } 25\ C, \ \pm 20 ppm \ over \ -40\ C \ to \ \pm 85\ C \\ U = \pm 50 ppm \mbox{ at } 25\ C, \ \pm 100 ppm \ over \ -40\ C \ to \ \pm 105\ C \\ X = \pm 50 ppm \mbox{ at } 25\ C, \ \pm 100 ppm \ over \ -40\ C \ to \ \pm 125\ C \\ Y = \pm 30 ppm \mbox{ at } 25\ C, \ \pm 50 ppm \ over \ -40\ C \ to \ \pm 125\ C \\ Y = \pm 30 ppm \mbox{ at } 25\ C, \ \pm 50 ppm \ over \ -40\ C \ to \ \pm 125\ C \\ \end{array}$

Packaging Options Blank = Bulk (Cut Tape) TR = Tape & Reel

Nominal Frequency

Load Capacitance

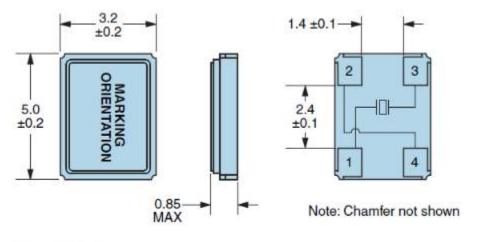
S = Series Resonant XX = 8pF Parallel Resonant to 32pF Parallel Resonant

Mode of Operation

A = AT-Cut Fundamental

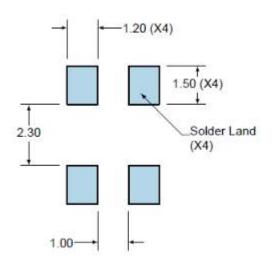


MECHANICAL DIMENSIONS



Seam Sealed Terminal Plating Thickness: Gold (0.3 to 1.0µm) over Nickel (1.27 to 8.89µm)

SUGGESTED SOLDER PAD LAYOUT



PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

All Tolerances are ±0.1

All Dimensions in Millimeters

EB3250 Series

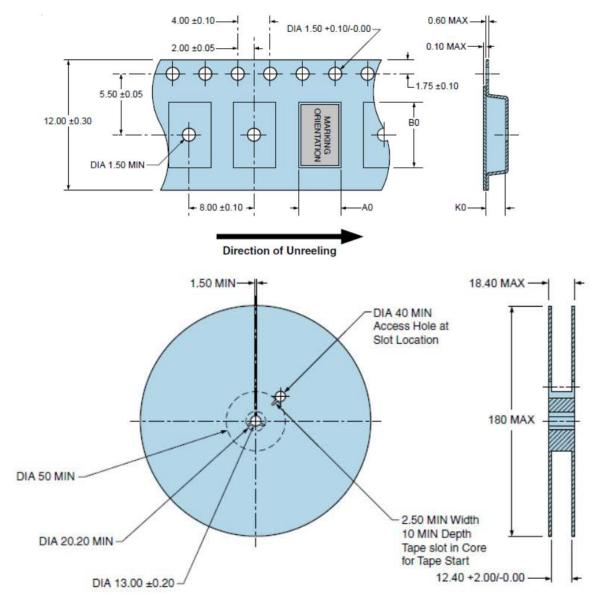


TAPE & REEL DIMENSIONS

Quantity per Reel: 1,000 Units

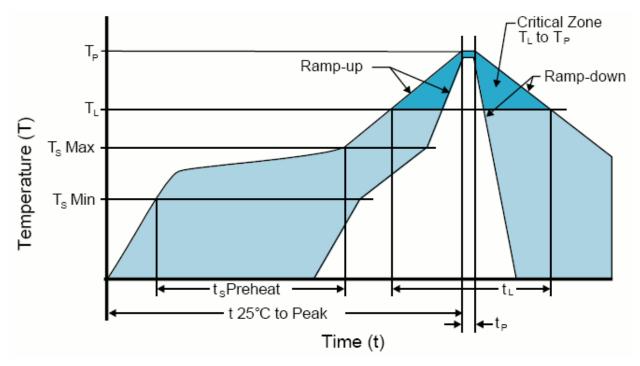
All Dimensions in Millimeters

Compliant to EIA-481





RECOMMENDED SOLDER REFLOW METHOD



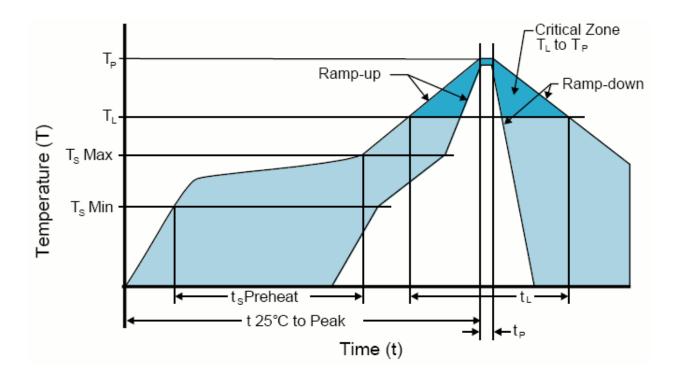
HIGH TEMPERATURE INFRARED/CONVECTION		
T_s MAX to T_L (Ramp-up Rate)	3°C/Second Maximum	
Preheat		
- Temperature Minimum (Ts MIN)	150°C	
 Temperature Typical (T_s TYP) 	175°C	
 Temperature Maximum(T_s MAX) 	200°C	
- Time (t _s MIN)	60 - 180 Seconds	
Ramp-up Rate (T _L to T _P)	3°C/Second Maximum	
Time Maintained Above:		
- Temperature (T∟)	217°C	
- Time (t∟)	60 - 150 Seconds	
Peak Temperature (T _P)	260°C Maximum for 10 Seconds Maximum	
Target Peak Temperature(T _P Target)	250°C +0/-5°C	
Time within 5°C of actual peak (t _p)	20 - 40 Seconds	
Ramp-down Rate	6°C/Second Maximum	
Time 25°C to Peak Temperature (t)	8 Minutes Maximum	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



RECOMMENDED SOLDER REFLOW METHOD



LOW TEMPERATURE INFRARED/CONVECTION		
T_s MAX to T_L (Ramp-up Rate)	5°C/Second Maximum	
Preheat		
- Temperature Minimum (Ts MIN)	N/A	
- Temperature Typical (T _s TYP)	150°C	
- Temperature Maximum(T _s MAX)	N/A	
- Time (t _s MIN)	30 - 60 Seconds	
Ramp-up Rate (T _L to T _P)	5°C/Second Maximum	
Time Maintained Above:		
- Temperature (T∟)	150°C	
- Time (t _L)	200 Seconds Maximum	
Peak Temperature (T _P)	245°C Maximum	
Target Peak Temperature(T _P Target)	245°C Maximum 2 Times/230°C Maximum 1Time	
Time within 5°C of actual peak (t _P)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time	
Ramp-down Rate	5°C/Second Maximum	
Time 25°C to Peak Temperature (t)	N/A	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)